

A Sub-threshold Variation-tolerant 16-channel FIR Filter Core for Hearing Aids

EECS 627

Group 6

Abhijith, Naveen, Susan, Bjorn, QJ

Overview

- Motivation
- Novelty & Value
- Specifications
- FIR Algorithm & Golden Brick Model
- Top Level Architecture
- Circuit Design & Analysis:
 - On-chip Switched-Capacitor DC-DC Converter
 - Sub-threshold 8T SRAM
 - Global Corner Detection
- Verification
- Floor Plan
- Results

Motivation

- Motivation:
 - Design of a low-power FIR filter core ASIC for Implantable hearing aids.
- Design Considerations:
 - Energy Constrained:
 - Battery-powered => Minimize Energy/FIR operation
 - Small Form-Factor:
 - Reduce package size, eliminate large off-chip components.
 - Global Process Variation tolerance:
 - Correlate critical-path delay with global process variation, reduce design-time margining.
- Key Metrics: Power, Reliability and Area while maintaining the required throughput.

Novelty and Value

➤ Novelty:

- Custom dual-banked ultra-low leakage sub-threshold 8T SRAM.
- On-Chip Switched Capacitor DC-DC Converter for Multi-VDD.
- Global Corner detector and controller to set on-chip supply.

➤ Improvements over Previous designs:

- Low power consumption permits integrated DC-DC converter
 - reduces packaging size, cost and complexity.
- Banked SRAM improves memory BW, small area overhead.
- Reduction in the energy consumed by the SRAM during Read and Write operations.
- On chip corner detection circuit for calibrating supply voltage at Power-On.

Specifications

- Input Data: 16 kHz sampled 16-bit Discrete Time data from ADC *
- Output Data: 16 channel 16-bit filtered data to output DACs *
- Core Area: $< 1\text{mm}^2$
- Core Frequency: 910 kHz
- Core Supply Voltages: 0.28 V , 0.33 V, 0.38 V
- Battery-Supply: 1.2 V
- Operating Temperature: 37°C
- 2kb 8T SRAM operating at subthreshold
- Process: IBM® 0.13um 8-metal CMOS , ARM Artisan® Standard Cell Library

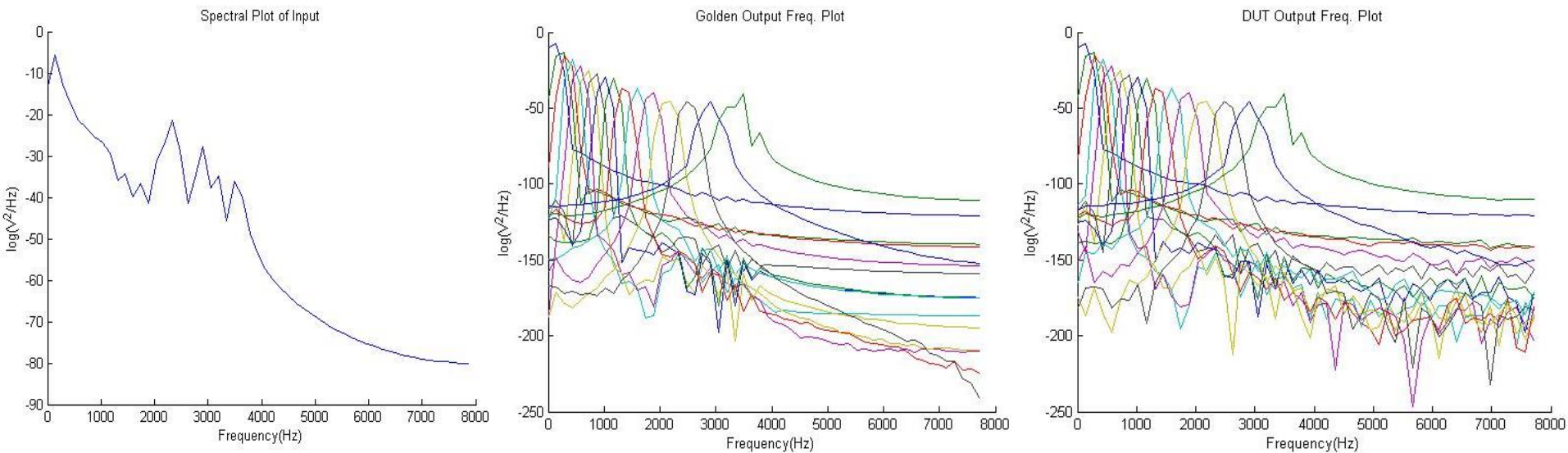
* ADC/DAC not implemented in this chip.

Algorithm and Model

- FIR Operation: Convolves input data pairs with filter coefficient vector h

$$y[n] = \sum_{i=1}^{N/2} h[i] * \{x[n - i] + x[n - N - i]\}$$

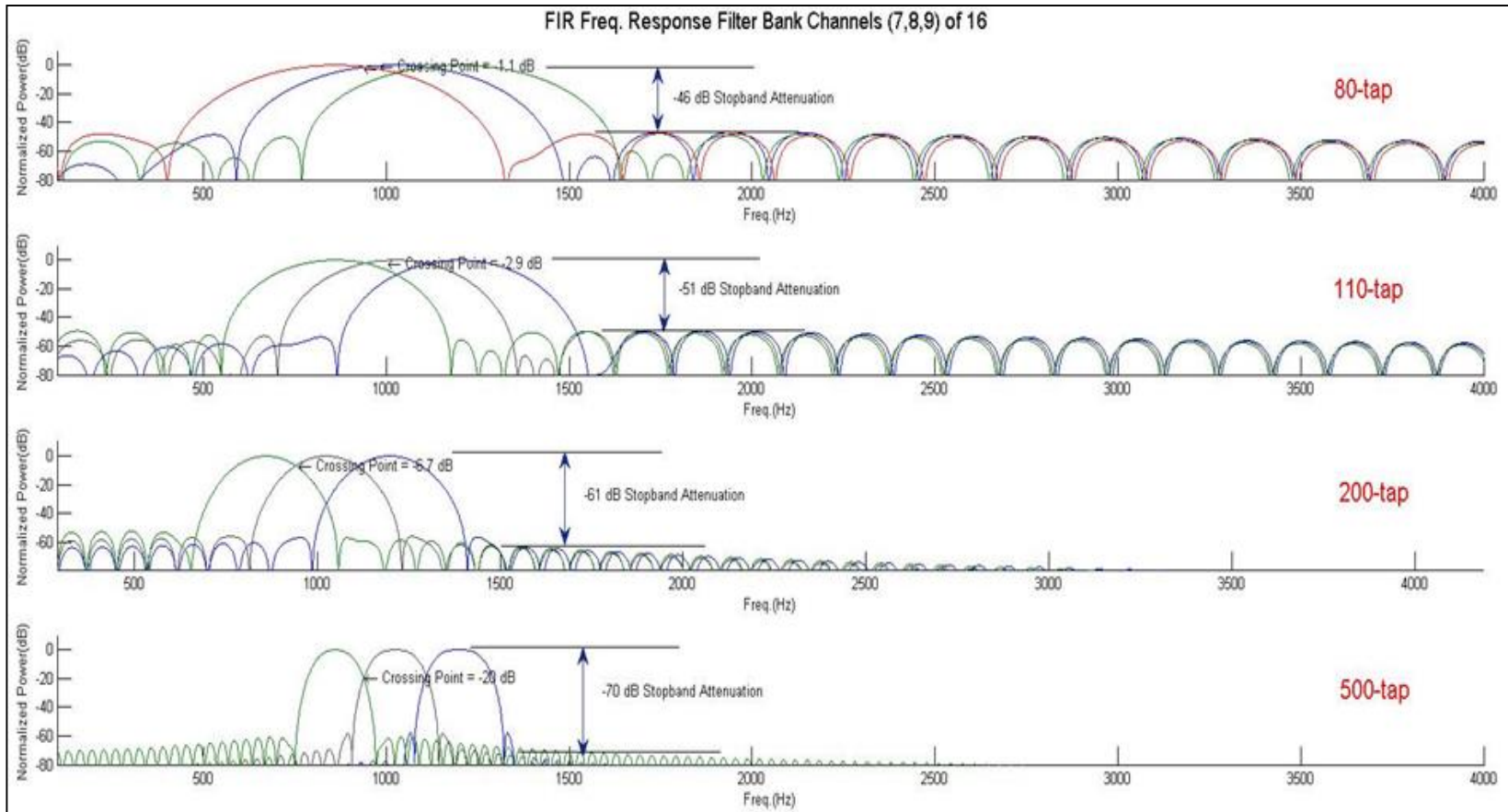
- 16-Channel Band Pass FIR Filters across human speech frequency range.
- Golden Brick – 16-bit fixed-point model using MATLAB & Simulink FDA tool.



MATLAB Simulation of 16 channel FIR Filter & HDL Implementation with same input stimulus

Algorithm and Model

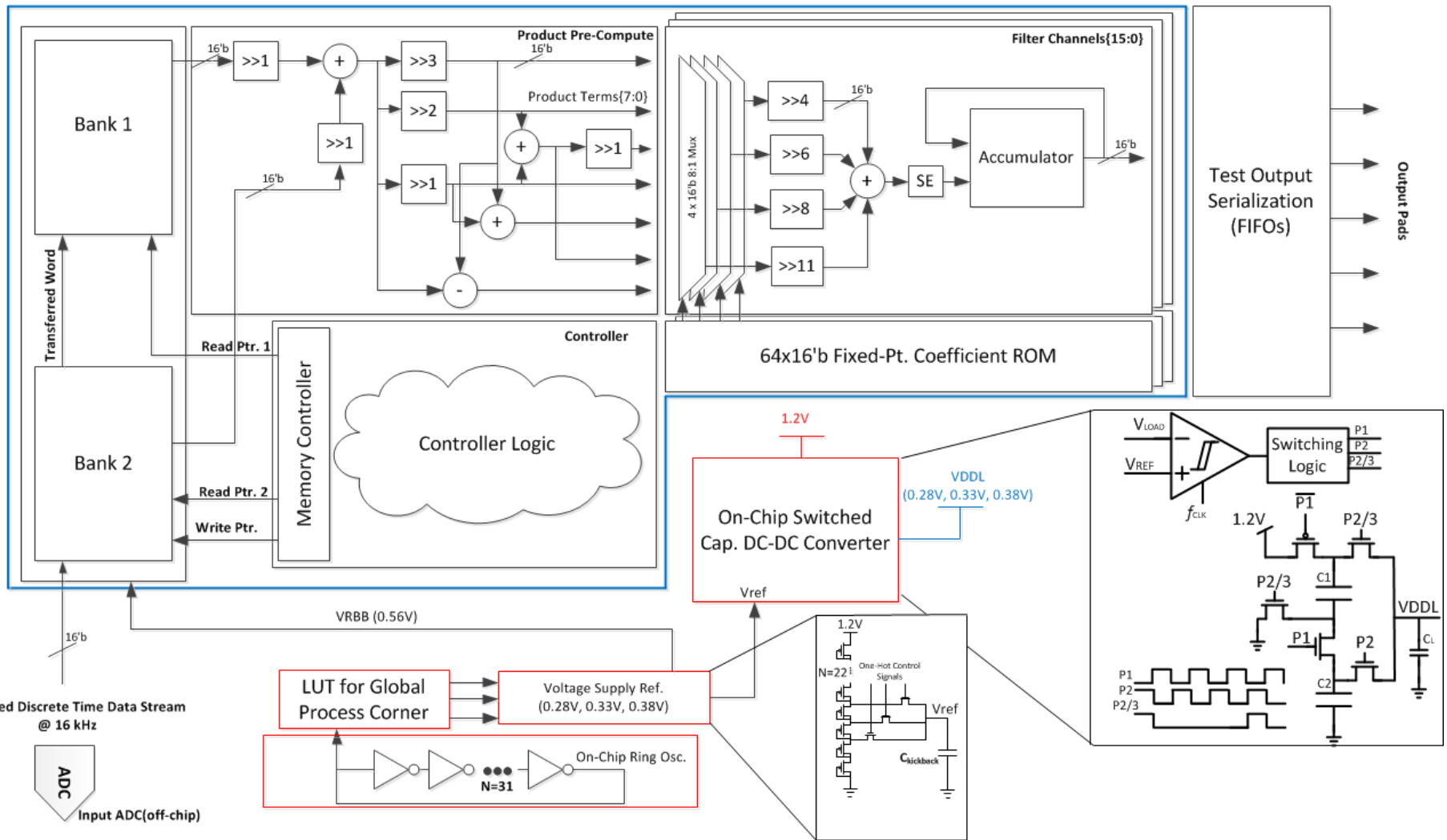
- FIR Filter Response: >50 dB of Stop-band Attenuation and 3 dB crossover attenuation
- Filter Order $< \text{Max. Core Clock Frequency} / 16 \text{ kHz Sampling Frequency}$



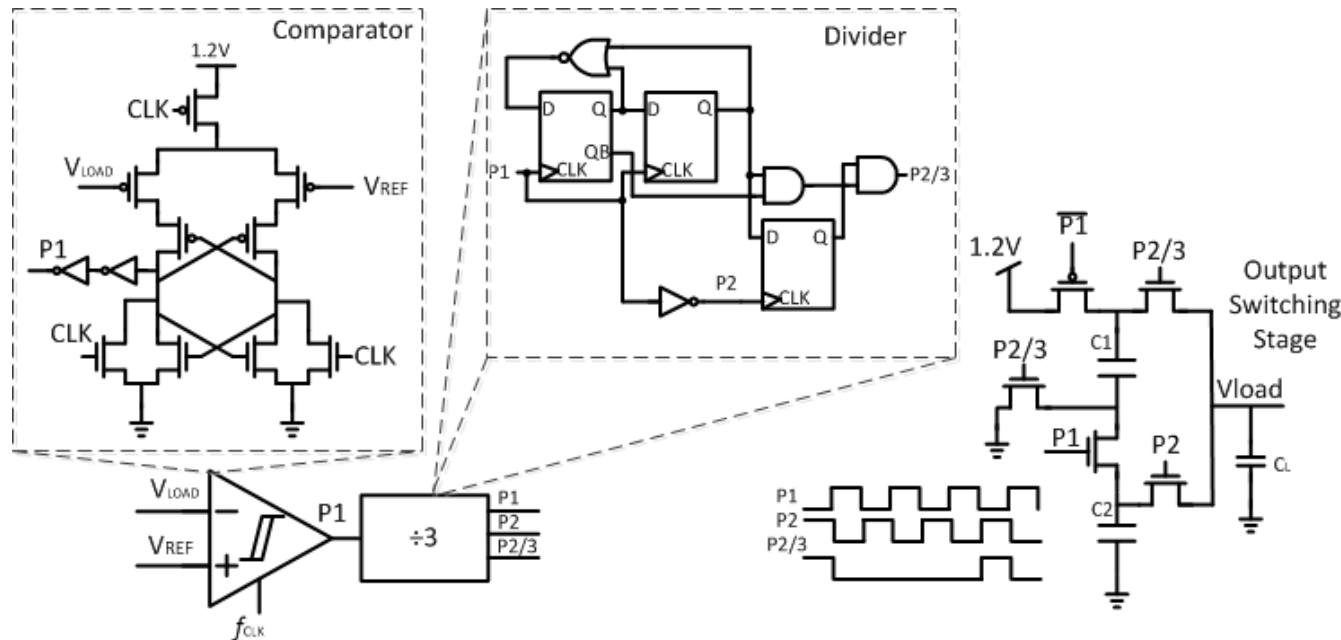
Filter response for various orders

Top-level Architecture

Custom Subthreshold
2kb 8T SRAM

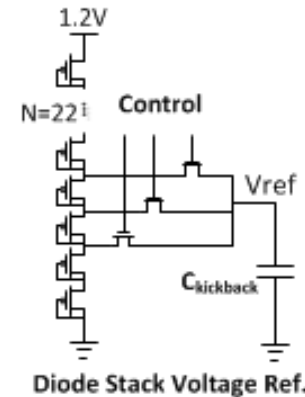
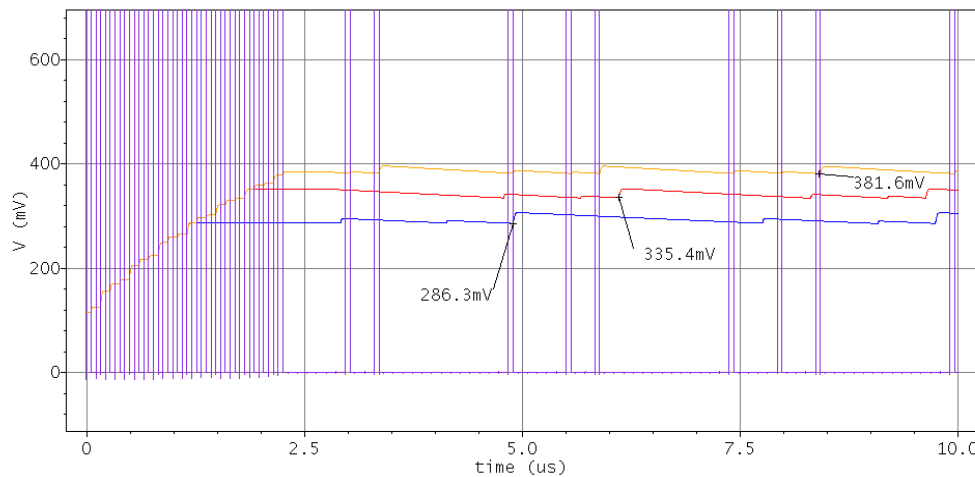


On-Chip DC-DC Converter



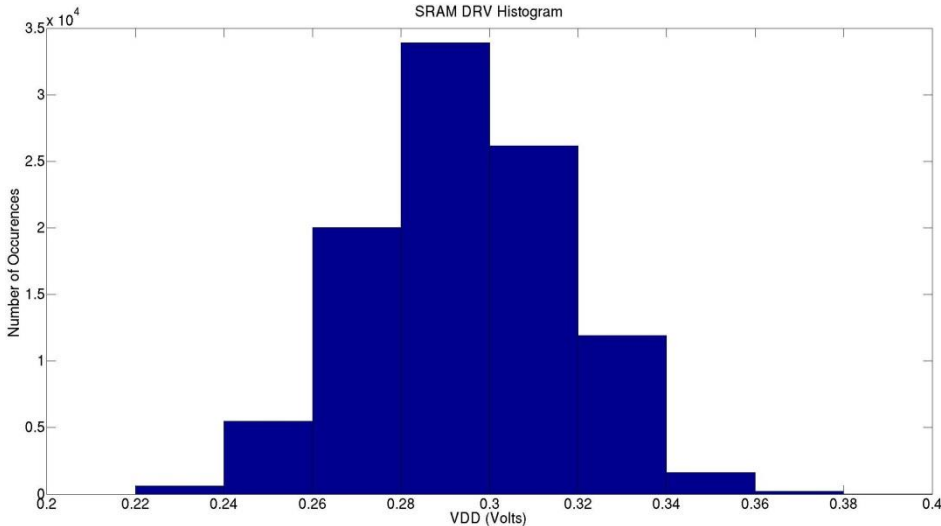
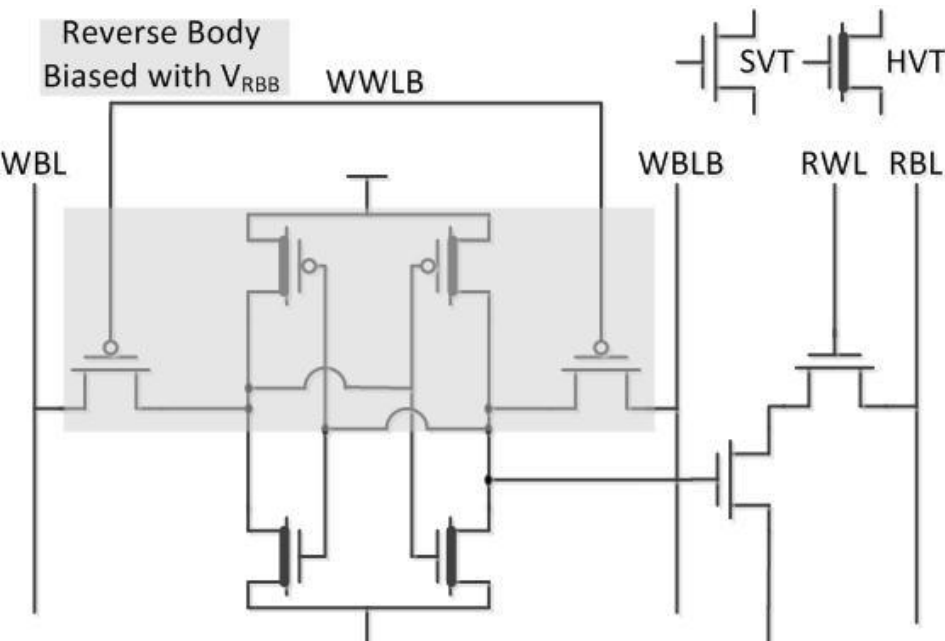
Transient Response

— $V_T("v_{out"}) < 0$ — $V_T("v_{out"}) < 1$ — $V_T("v_{out"}) < 2$ — $V_T("I_{91}/\phi_{11}")$



- Regulates V_{LOAD}
- Sources of Loss:
 - Charge-transfer switching loss
 - Bottom-plate sampling loss
 - MOS capacitor leakage
- $C_{kickback}$ reduces supply kickback noise
- Recharge pulses only when falls V_{LOAD} below V_{REF}
- Switching Efficiency: 46%(0.28V) – 55%(0.38V)

SRAM

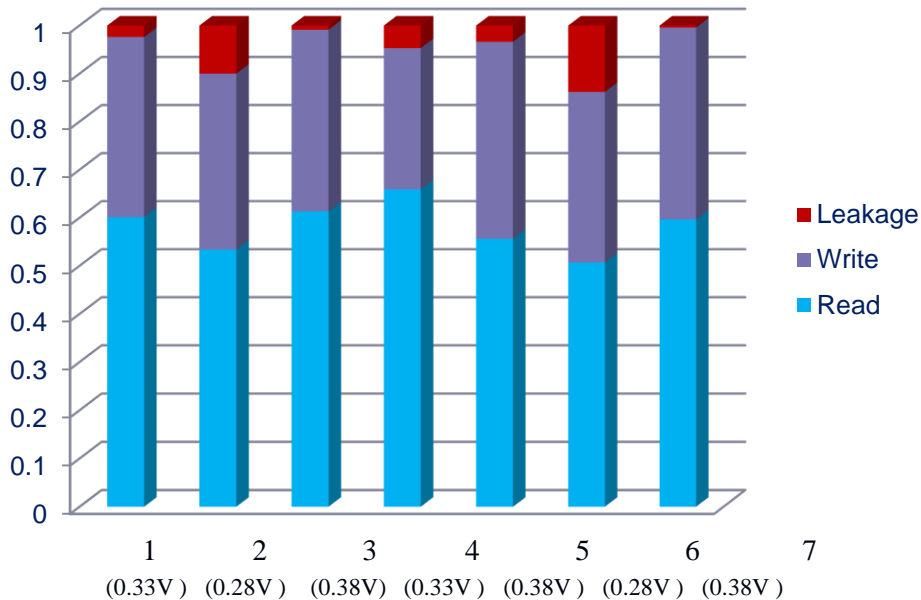


- **Cross Coupled Invertors*** – HVT Transistors for low leakage.
- **SVT PMOS Access Transistor** – larger ON current.
- **2T Read Buffer** – SVT transistors for fast read.
- **Reverse Body Bias*** – low leakage.
- **Address Decoder** – Dynamic logic.

Height	1.54 μm
Width	4.26 μm
Area	6.5604 μm^2
Leakage (1 Bit-Cell)	0.93 pW
Avg. Energy/bit (Read)	15.996 fJ
Avg. Energy/bit (Write)	9.978 fJ
Aspect Ratio	2.766

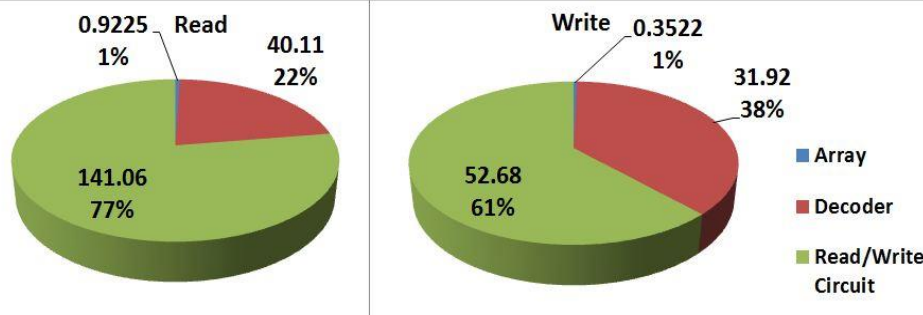
*Daeyeon Kim et al. "A 1.85fW/bit Ultra Low Leakage 10T SRAM with Speed Compensation Scheme," Circuits and Systems (ISCAS), 15-18 May 2011.

Analysis: SRAM

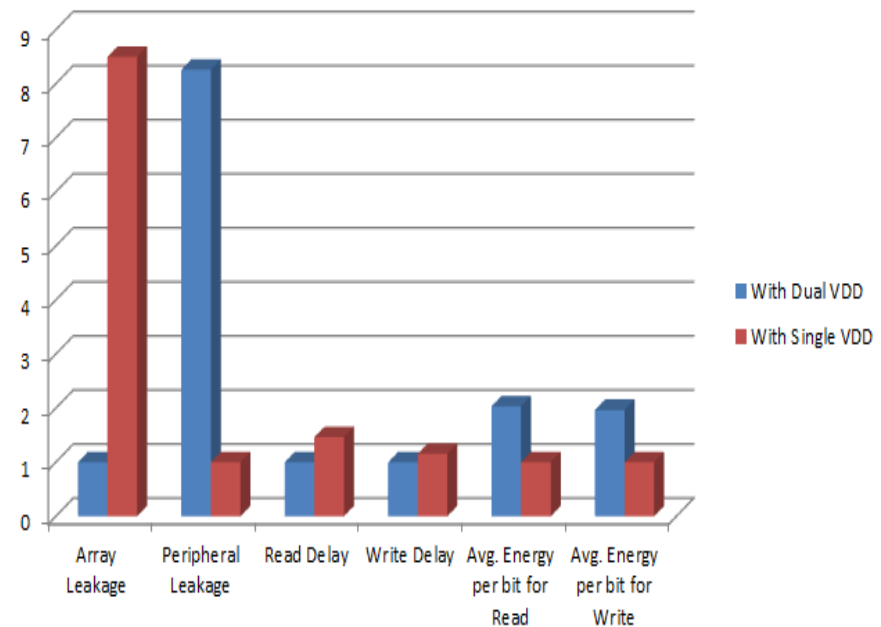


Normalized energy consumption (per bit) at various corners with corresponding V_{DD}

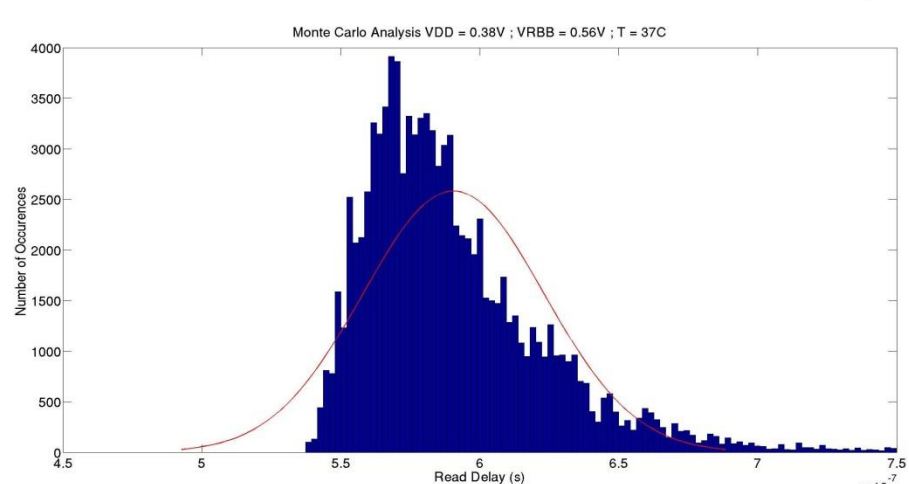
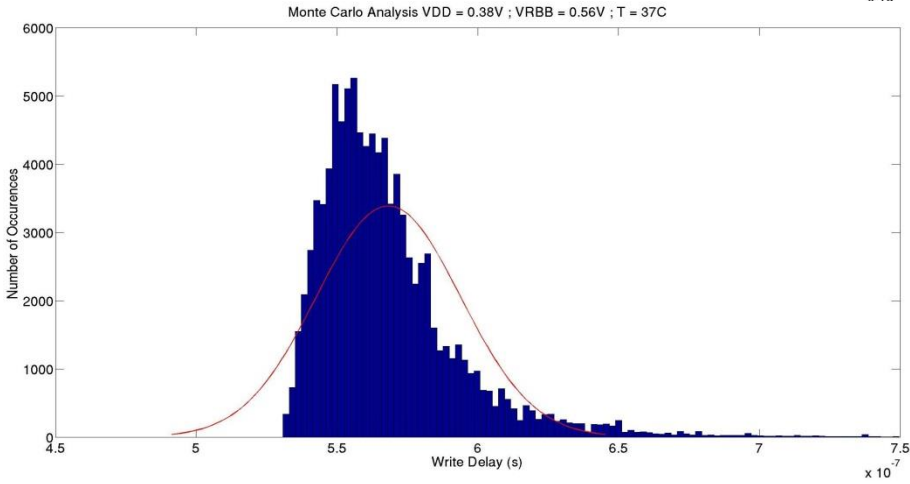
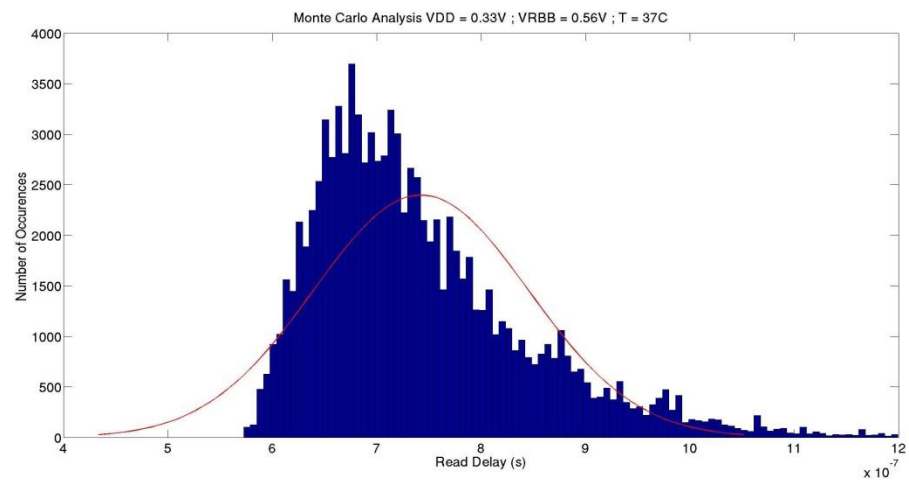
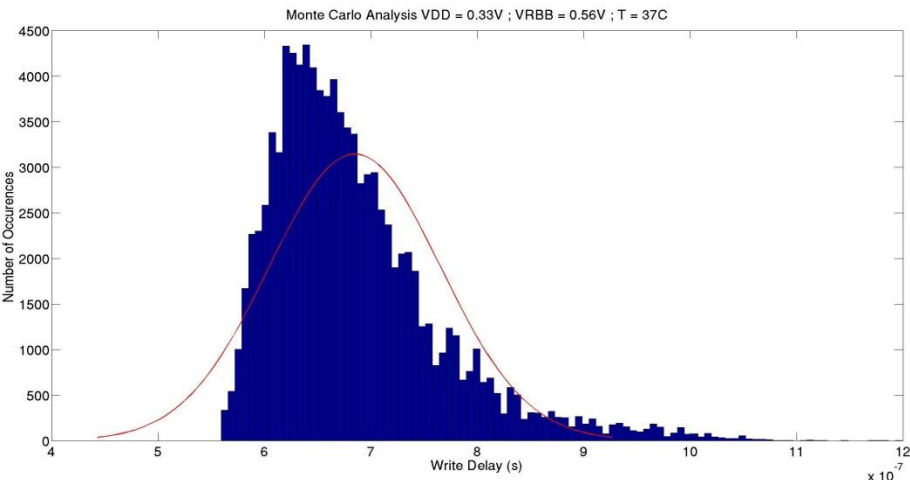
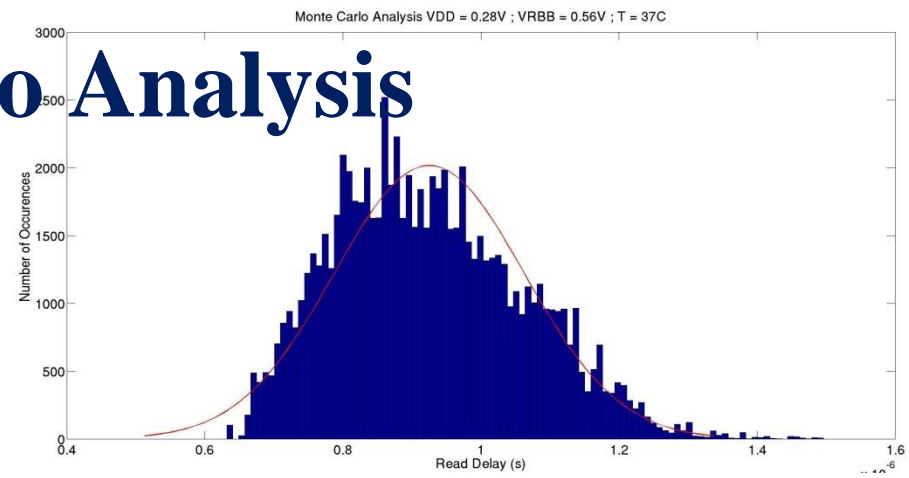
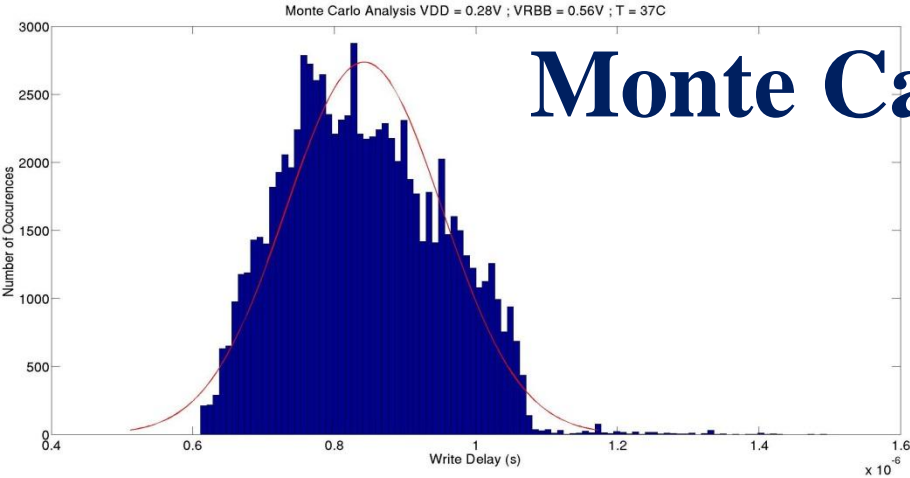
Array Size	56 words x 16 bits
SRAM Height	131.54 μm
SRAM Width	116.55 μm
Array Efficiency	~74%
V_{DD}	0.28V/0.33V/0.38V
V_{RBB}	0.56V
Access Scheme	1R/1W



Energy consumed by various SRAM components (Entire Array) in fJ

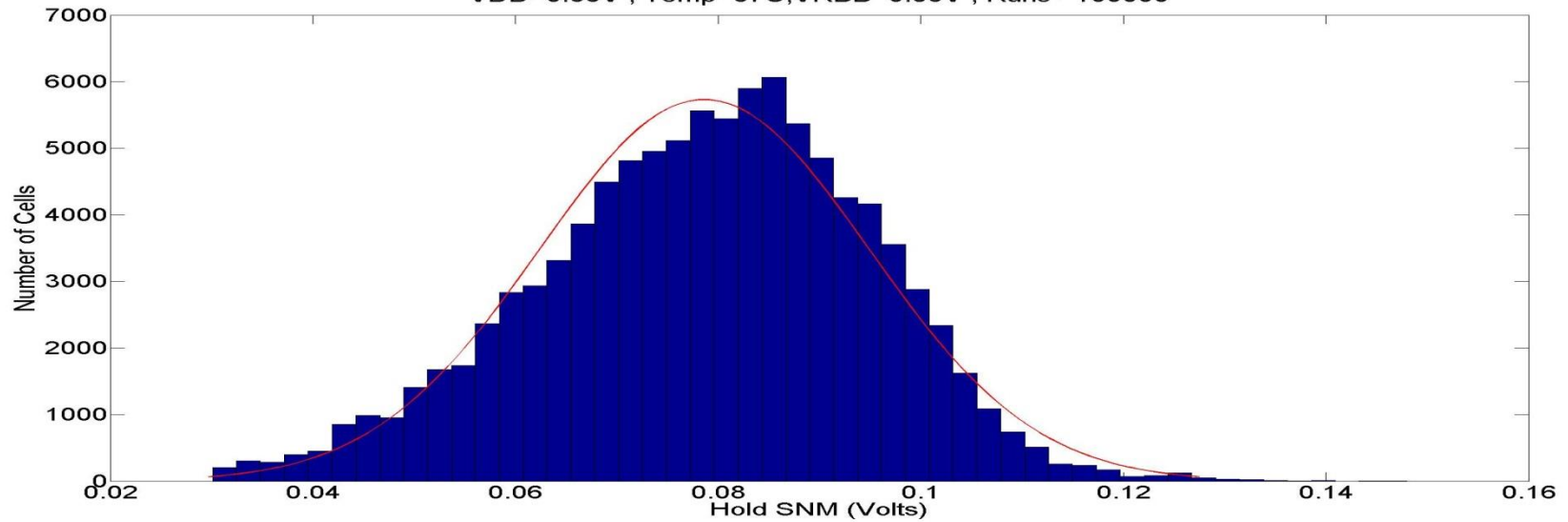


Monte Carlo Analysis

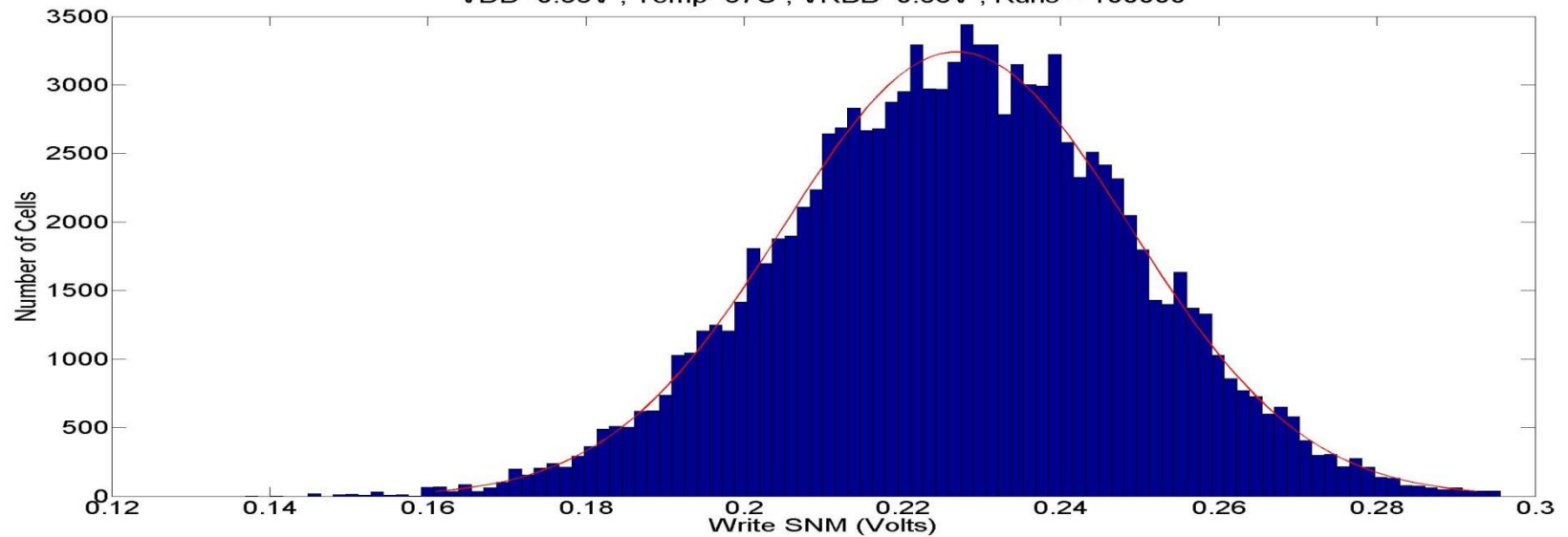


Monte Carlo Analysis

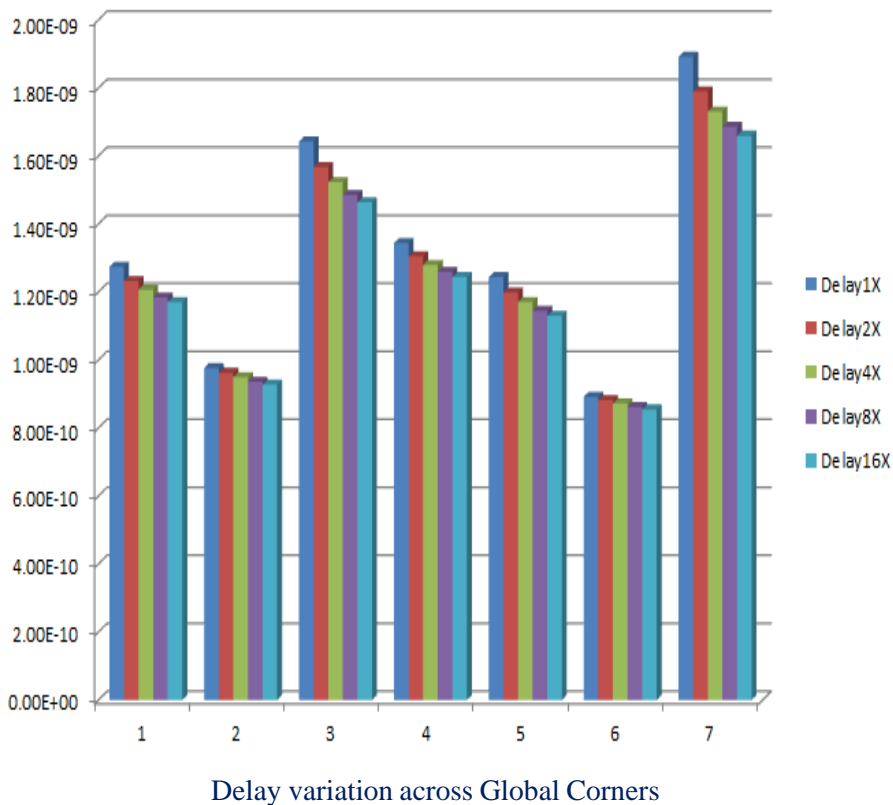
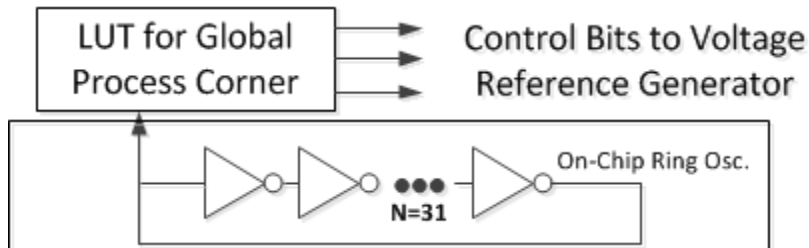
Monte Carlo Analysis for Hold SNM
VDD=0.33V ; Temp=37C; VRBB=0.56V ; Runs = 100000



Monte Carlo Analysis for Write SNM
VDD=0.33V ; Temp=37C ; VRBB=0.56V ; Runs = 100000

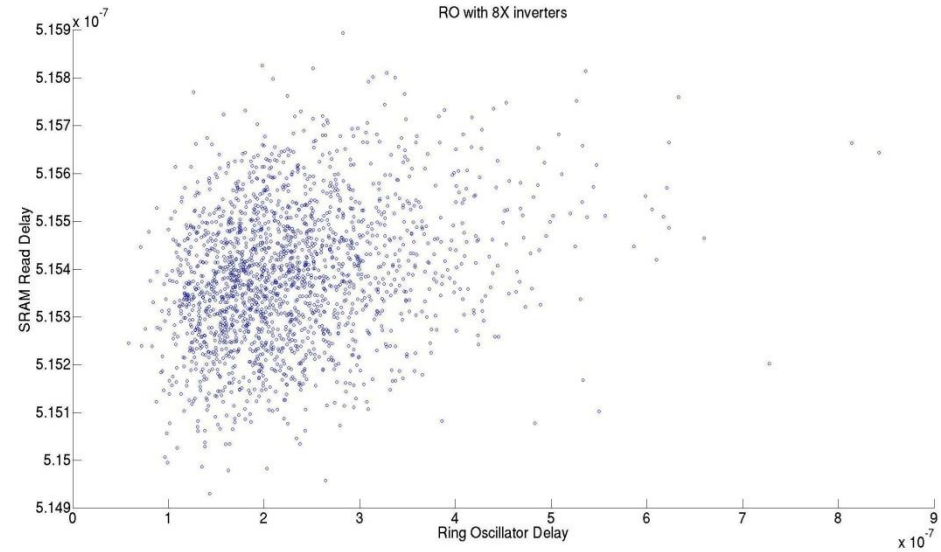
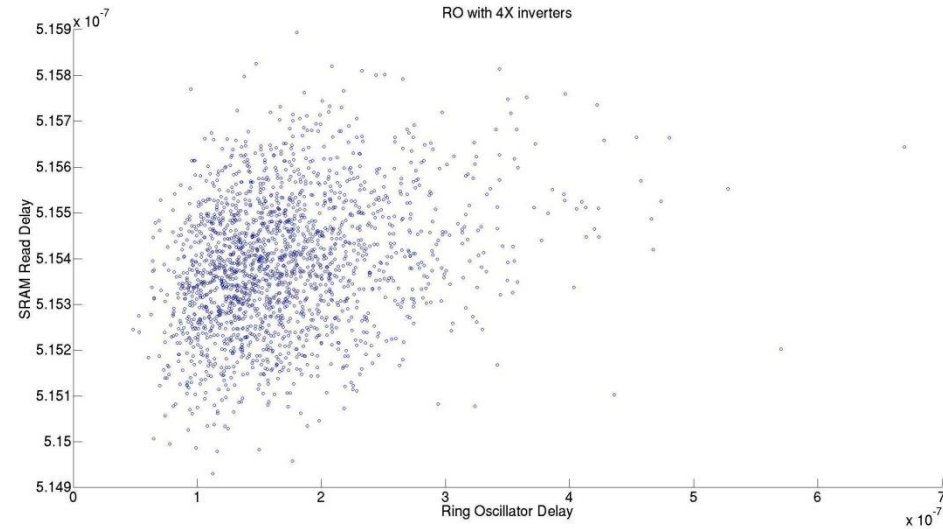
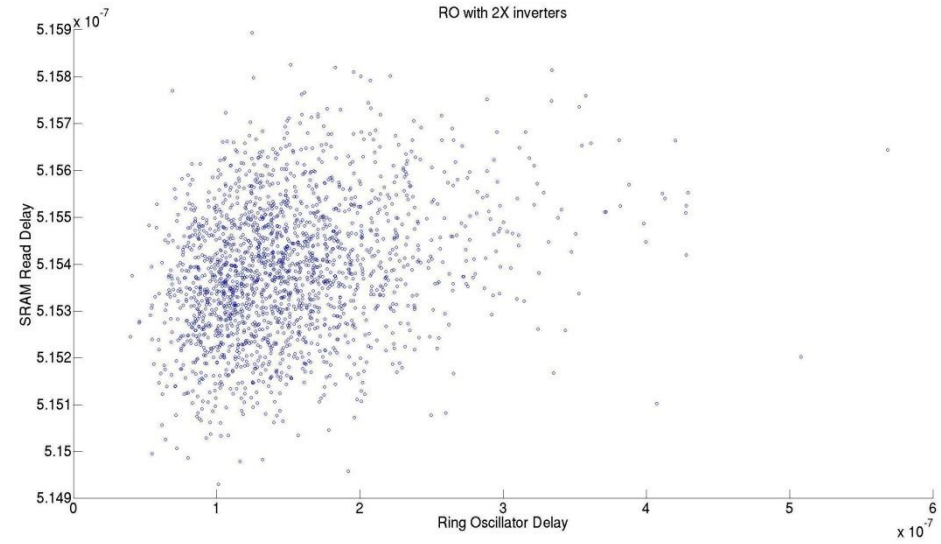
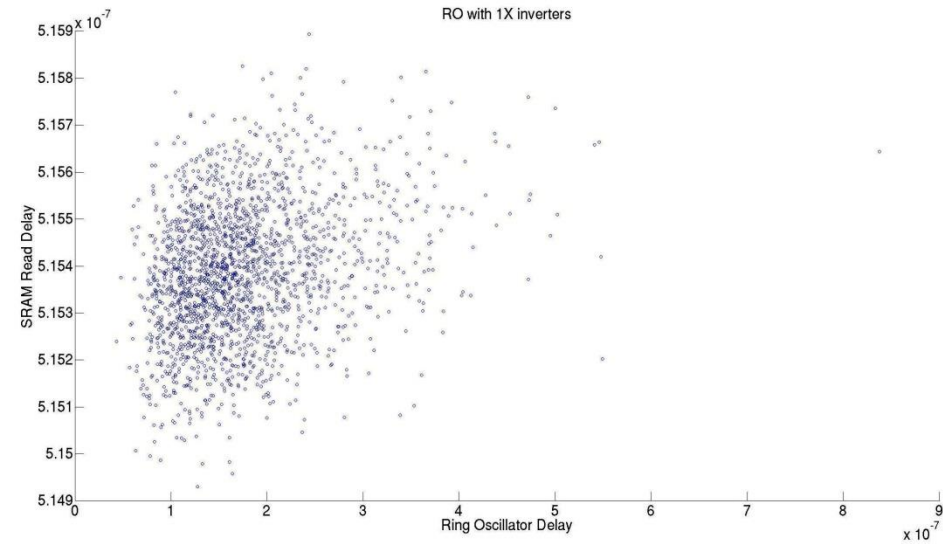


Corner Detection



- Target inter-die variations -
 - Fixed workload.
 - Temperature invariant ($\sim 37^{\circ}\text{C}$)
 - Primary sources of variation can be:
 - device ageing
 - L_{di}/dt
 - IR.
- *Ring Oscillator* – 31 Stages , 4x Sized.
- *Controller* - 10 Bit Counter with a reset.
- *Power Domain* – Powered by 1.2 V supply.
- *Reset* - keep this signal high for 2 clock cycles until the controller does the calibration and sends the control signal to the DC-DC converter.
- *Testing Time* - Requires only 2 clock cycles to calibrate the chip (one clock cycle to detect the corner, one clock to set the reference).

Global Variation Correlation: RO vs Critical Path



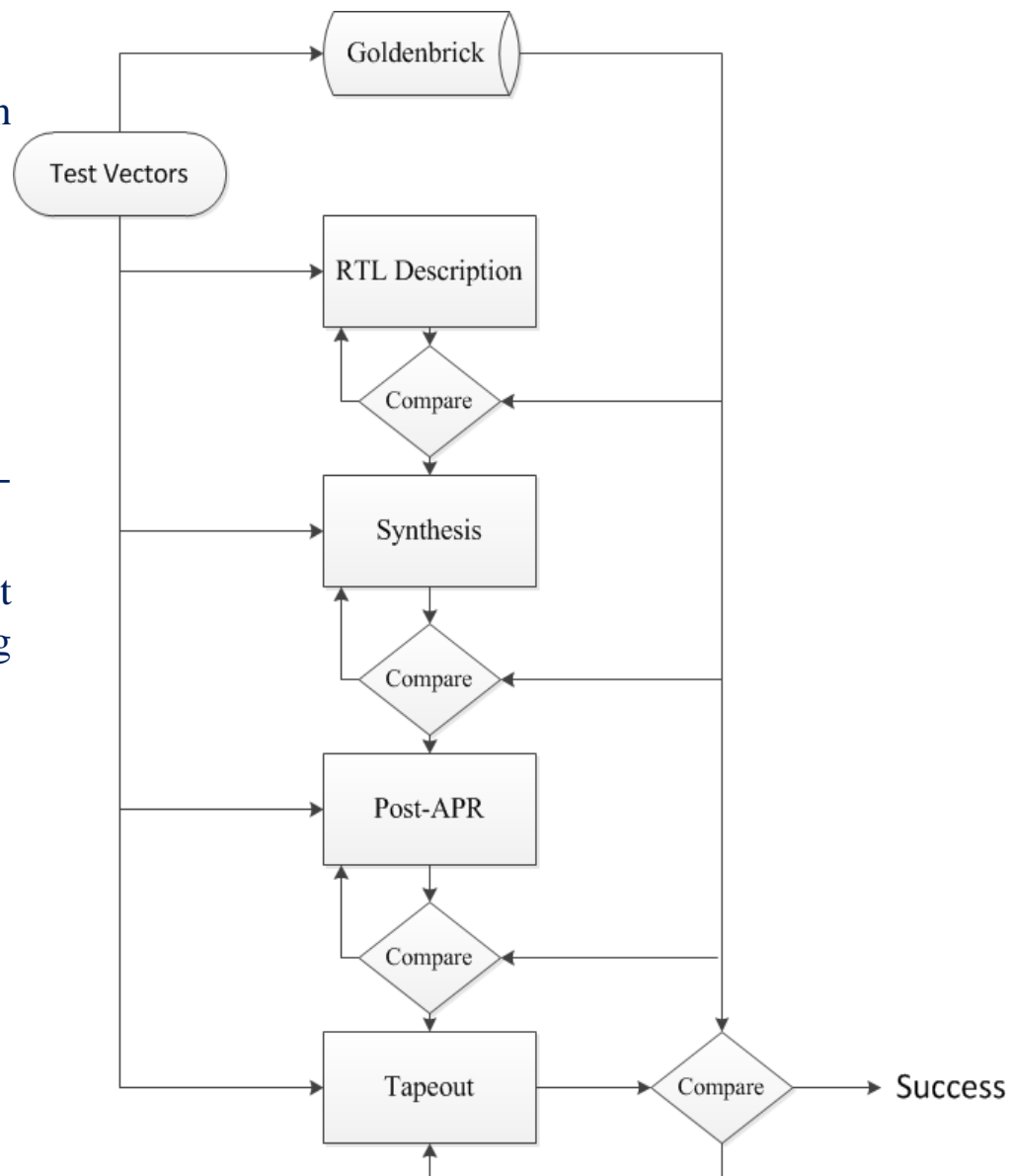
Verification

➤ Data representation –

- Input/Output/Coefficients of FIR are in fixed-point decimal representation.
- Input/Coefficients – 16bits (Q15).
- Output – 16bits (Q15).

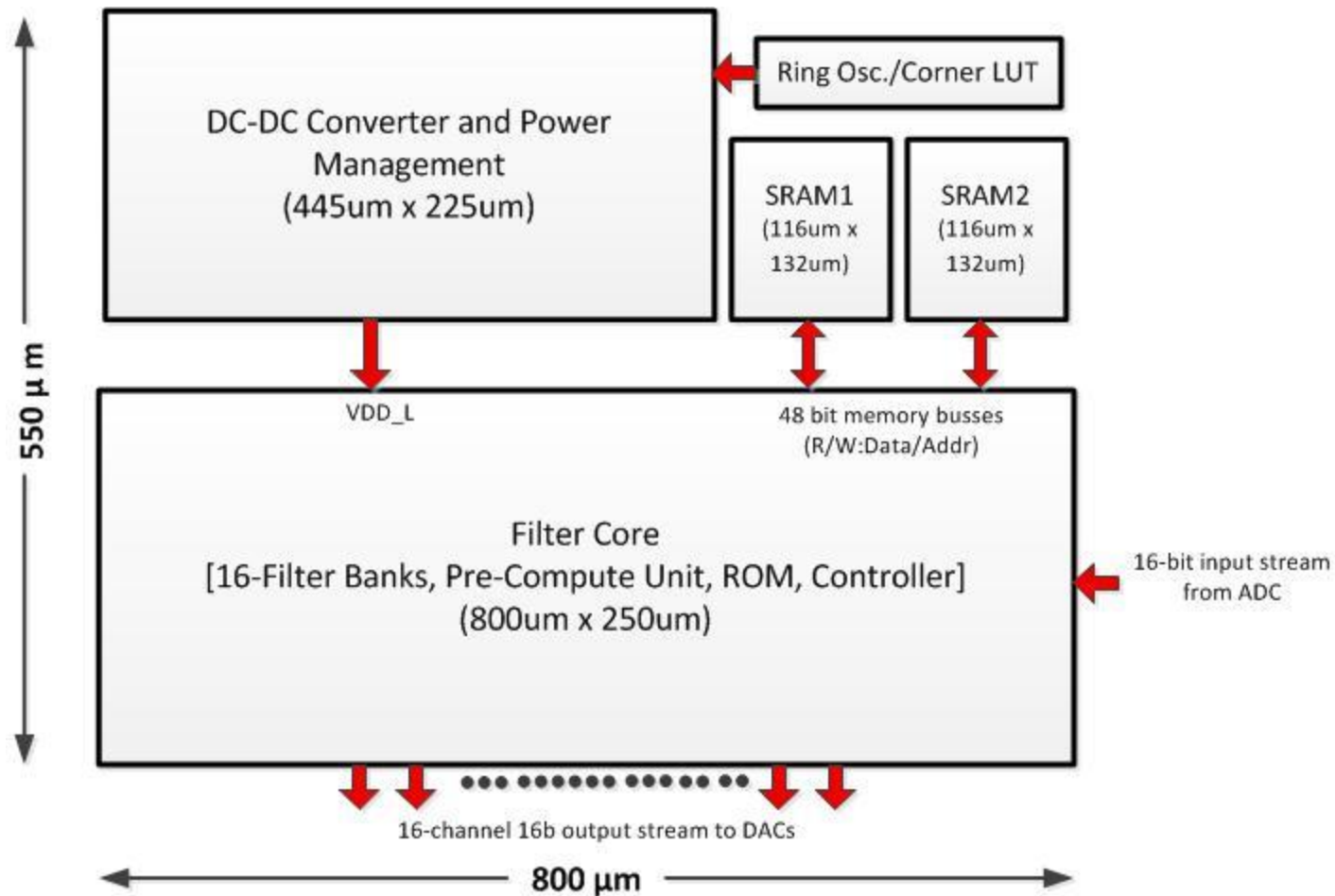
➤ Test of functionality

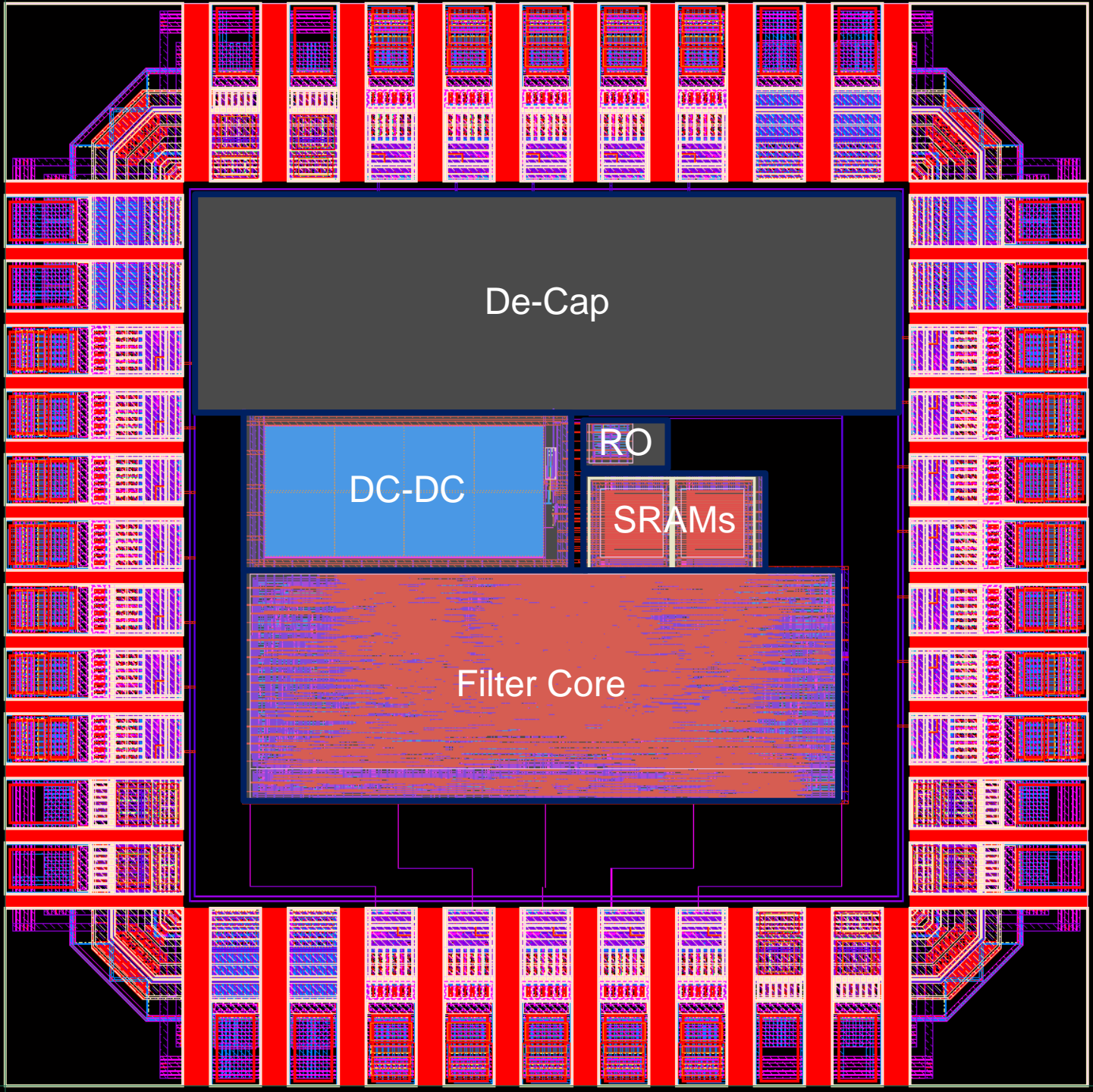
- Input test vectors generated from real-time signals using MATLAB.
- Compare the Behavioral Model output with the MATLAB Golden brick fixing an allowable error rate.



Floor plan/Layout

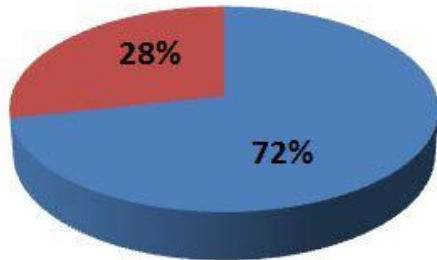
➤ Core Area – 0.45 mm²





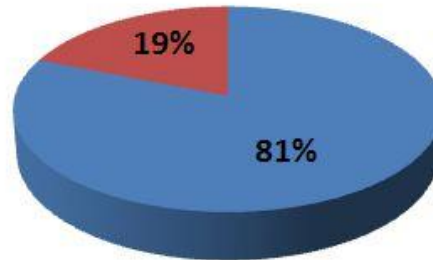
Results : Power

FIR Core Power (0.28V)



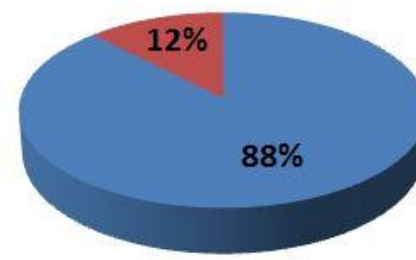
Total Power: 5.12 uW

FIR Core Power (0.33V)



Total Power: 10.07 uW

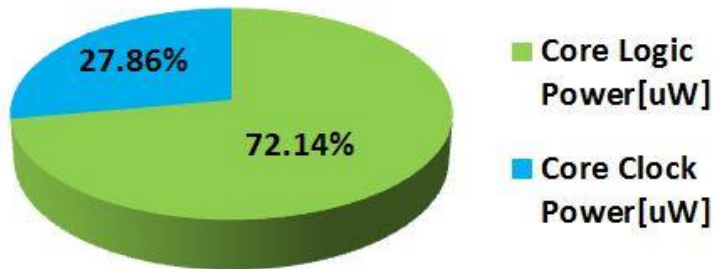
FIR Core Power (0.38V)



Total Power: 19.65 uW

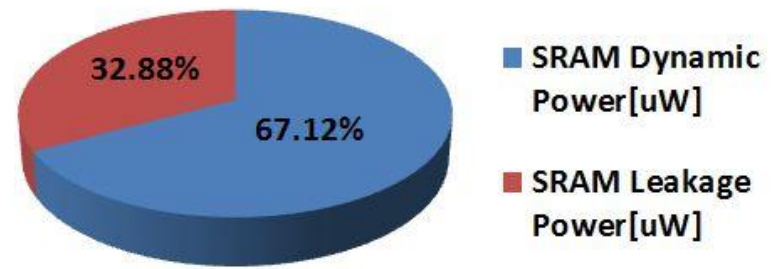
■ Core Dynamic Power[uW](RMS)
■ Core Leakage Power[uW](RMS)

Core Power Breakdown



V_{DD} = 0.28 V

2kb SRAM Power Consumption

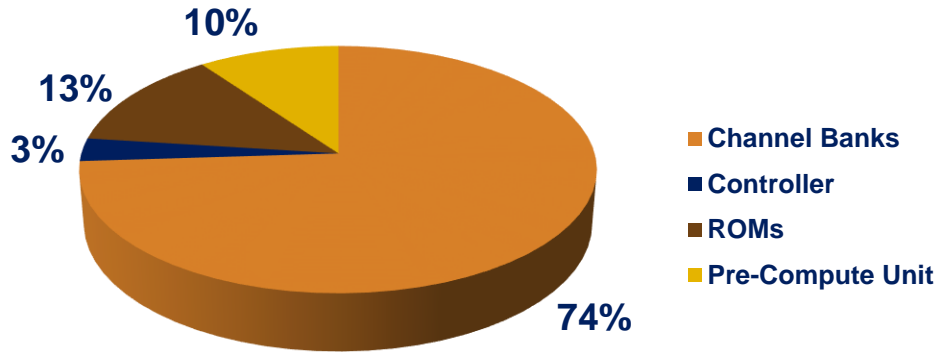


Total Power: 87 pW

■ SRAM Dynamic Power[uW]
■ SRAM Leakage Power[uW]

Results: Power

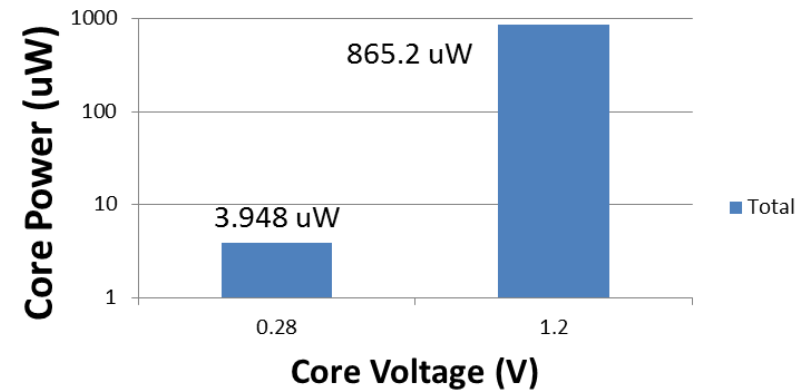
Core Power Breakdown



$P_{avg} = 10.1 \mu W$

$V_{DD} = 0.33 V$

Nominal vs. Sub-threshold Power



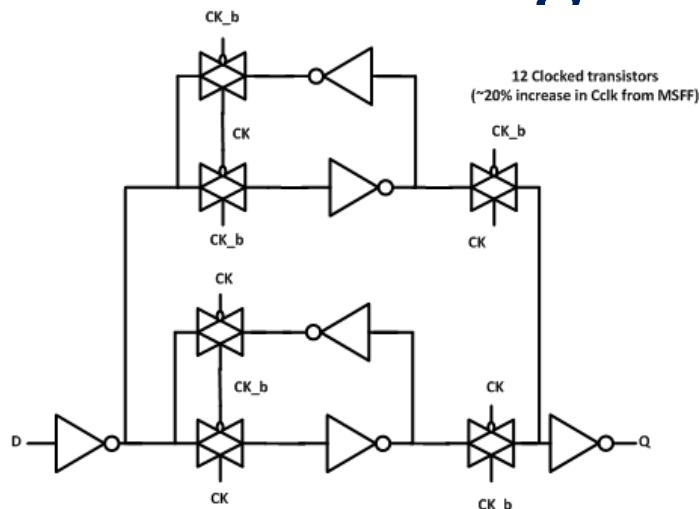
Comparison to Previous Subthreshold FIR Cores

Design	Supply Voltage (V_{DD})	Process Node	Filter Order/Word Length	Avg. Power	Core Freq. (f_{clk})	Energy/FIR operation
Chong et. al	0.3 V	65 nm	109 th /16b	10.4 μW	960 kHz	0.6 nJ
Myeong-Eun Hwang et. al	85 mV – 1.2 V	130 nm	8 th /8b	40 nW	240 Hz	1.33 nJ
Proposed Design	0.28 V – 0.38 V	130 nm	109th/16b	5.1 μW – 19.7 μW	910 kHz	0.31 nJ – 1.19 nJ

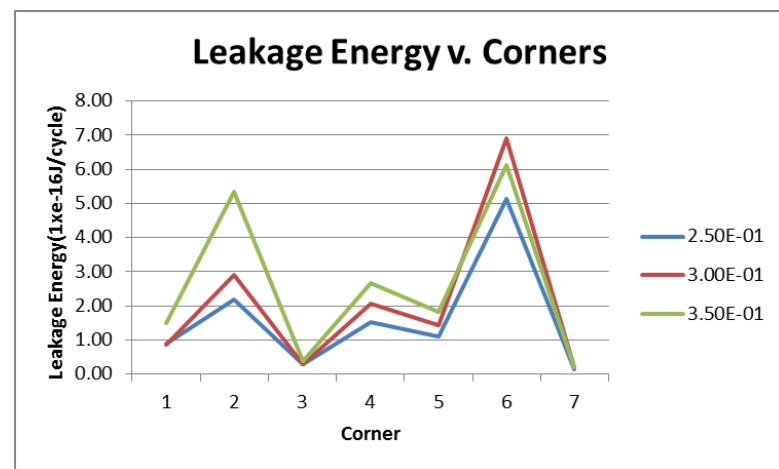
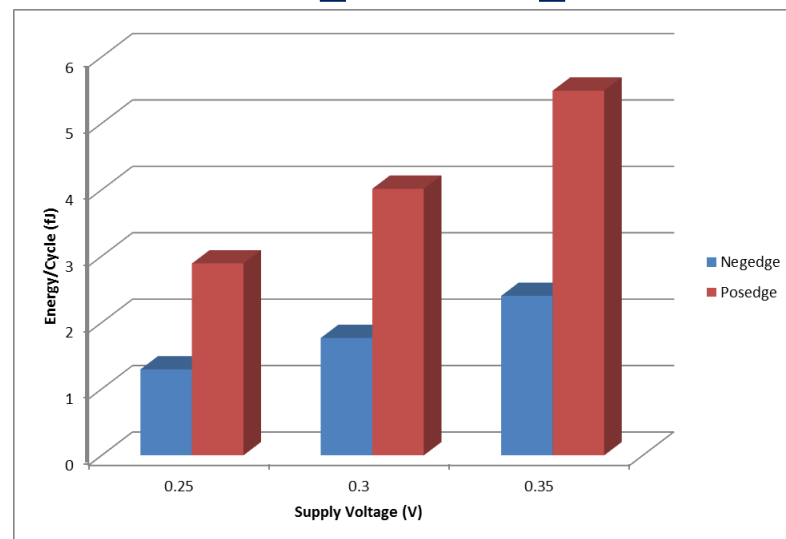
Thank You!

Backup

Dual Edge Triggered Flip-Flop



- Fixed-throughput means no clock-gating and relatively high activity factor.
- DETFF can reduce clock power up to ~30%.
- Implementation Plan: Integrate within filter bank module to compare relative improvement.
- Initially thought of using this but since Clock power was < 30% of total power and we would end up saving lesser than what we would spend in bringing this up!



Output FIFO

Problem :

256 output data signals of top module :

y_out[255:0] – Need too much pads !

**Solution : use output FIFOs, 5 output FIFOs :
need only 5 pads !**

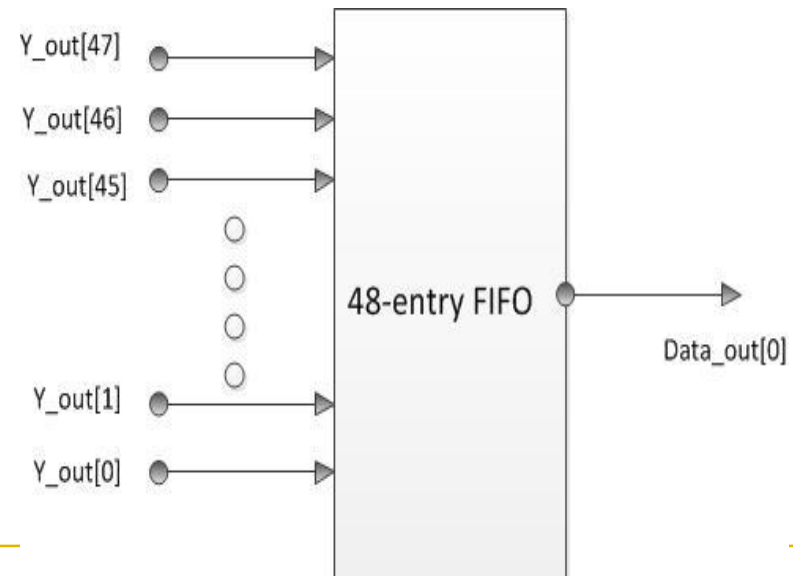
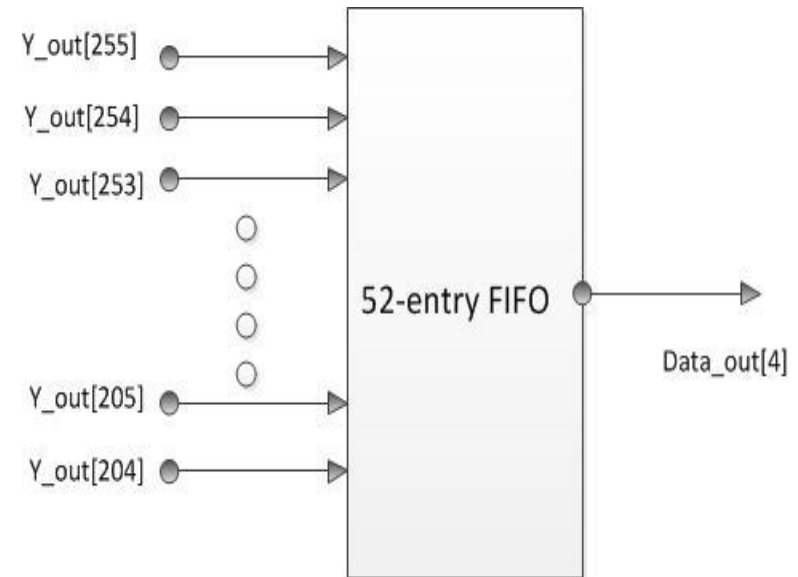
Output data signals change every 56 clock cycles

fifo style I : 4 52 entries FIFOs

fifo style II : 1 48 entries FIFO

**Write to the fifo at a time, read the data to pad
every clock cycle**

- length : 820 μm
- width : 42 μm
- area : 34,440 μm^2



Future Work

➤ Future Work:

- Implement ADC/DACs on-chip to integrate system.
- Integrate low-power on-chip PLL for local clock generation.

References

- [1] Kwen-Siong Chong; Bah-Hwee Gwee; Chang, J.S., "A 16-Channel Low-Power Nonuniform Spaced Filter Bank Core for Digital Hearing Aids," Circuits and Systems II: Express Briefs, IEEE Transactions on, vol.53, no.9, pp.853-857, Sept. 2006.
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- [3] Yu-Ting Kuo; Tay-Jyi Lin; Yueh-Tai Li; Chih-Wei Liu, "Design and Implementation of Low-Power ANSI S1.11 Filter Bank for Digital Hearing Aids," Circuits and Systems I: Regular Papers, IEEE Transactions on , vol.57, no.7, pp.1684-1696, July 2010.
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- [5] Tong Lin et. al., "An Ultra-Low Power Asynchronous-Logic In-Situ Self-Adaptive VDD System for Wireless Sensor Networks", Solid-State Circuits, IEEE Journal of, vol. 48, no. 2, February 2013.
- [6] Daeyeon Kim et al. "A 1.85fW/bit Ultra Low Leakage 10T SRAM with Speed Compensation Scheme", Circuits and Systems (ISCAS), IEEE International Symposium on, May 2011.
- [7] Ramadass, Y.K.; Chandrakasan, A.P.; , "Voltage Scalable Switched Capacitor DC-DC Converter for Ultra-Low-Power On-Chip Applications," Power Electronics Specialists Conference (PESC), IEEE, vol., no., pp.2353-2359, 17-21 June 2007